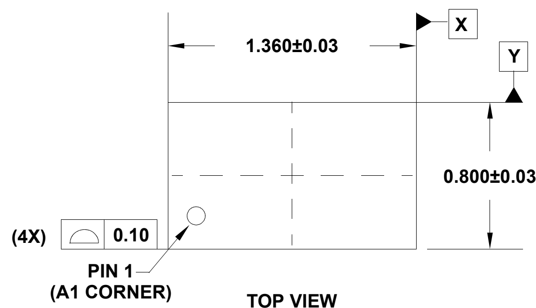
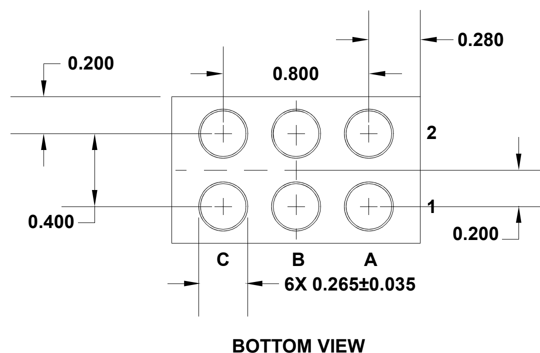
Package Outline Drawing

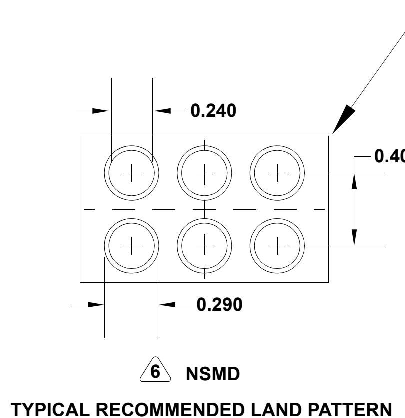
W3x2.6

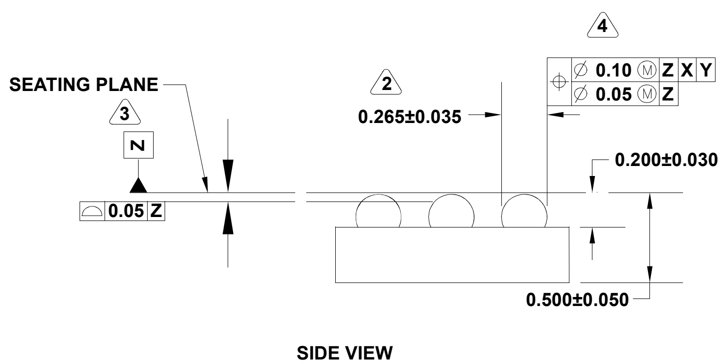
3x2 ARRAY 6 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLSCP 0.4mm Pitch)

Rev 3, 1/13









NOTES:

1. Dimensions and tolerance per ASME Y 14.5M - 1994.
2. Dimension is measured at the maximum bump diameter parallel to primary datum Z.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Bump position designation per JESD 95-1, SPP-010.
5. All dimensions are in millimeters.
6. NSMD refers to non-solder mask defined pad design per Intersil Tech Brief www.intersil.com/data/tb/tb451.pdf
7. Ball height and post saw device size can vary by ±10µm depending on final selection of assembly vendor.